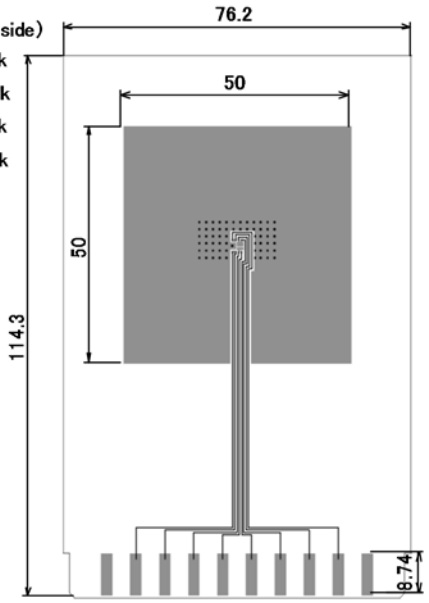
USP-8B10 Power Dissipation

Power dissipation data for the USP-8B10 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition:: Mount on a board
Ambient:: Natural convection
Soldering:: Lead (Pb) free
Board:: Copper foil 4 layer
demenshins 76.2mm × 114.3mm (about 8700mm^2 in one side)
1st inner layer : 50mm × 50mm connection with heat sink
2nd inner layer : 70mm × 70mm connection with heat sink
3rd inner layer : 70mm × 70mm connection with heat sink
4th inner layer : 50mm × 50mm connection with heat sink
Material: Glass Epoxy (FR-4)
Thickness: 1.6mm
Through-hole: ϕ0.2mm 60pcs



2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax = 125℃)

Ambient Temperature (℃)	Power Dissipation Pd(mW)	Thermal Resistance(℃/W)
25	1400	71.43
85	560